Welcome to ICECC 2021!

We are pleased to announce that The 4th International Conference on Electronics, Communications and Control Engineering (ICECC 2021) will be held in Seoul, South Korea during April 9-11, 2021.

ICECC is an annual conference launched in the year of 2018. We had this conference successfully held at Avid College, Maldives in 2018, in Phuket, Thailand in 2019, online (due to COVID-19) in 2020. It will provide a valuable opportunity for researchers, scholars and some scientists to exchange their ideas face to face together.

Keynote Speakers
- Prof. Yonghui Li, IEEE Fellow
  The University of Sydney, Australia
- Prof. Rui Zhang, IEEE Fellow
  National University of Singapore, Singapore
- Prof. Moshe Zukerman, IEEE Fellow
  City University of Hong Kong, Hong Kong

Proceedings
Accepted papers of ICECC 2021 (after proper registration and presentation) will be published in the International Conference Proceedings Series by ACM (ISBN: 978-1-4503-8912-9), which will be archived in the ACM Digital Library, and indexed by Ei Compendex, Scopus, etc.

The previous proceedings have all been indexed by Ei Compendex and Scopus.

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- Online Submission (click)

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